



Final Product/Process Change Notification

Document #: FPCN25163X

Issue Date: 15 Feb 2023

Title of Change:	Smart Power Stage Device Wirebond Change from Stand off Stitch Bond (SSB) to Forward Bonding on Leadpost.									
Proposed First Ship date:	22 May 2023 or earlier if approved by customer									
Contact Information:	Contact your local onsemi Sales Office or ArnulfoJr.Cabonillas@onsemi.com									
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.									
Additional Reliability Data:	Contact your local onsemi Sales Office or Aileen.Allado@onsemi.com									
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com									
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code									
Change Category:	Assembly Change									
Change Sub-Category(s):	Manufacturing Process Change									
Sites Affected:										
onsemi Sites		External Foundry/Subcon Sites								
onsemi Cebu, Philippines		None								
Description and Purpose:										
Capacity Improvement for manufacturing of SPS Packages by changing from Forward bond to Single Stitch Bond on Lead post										
<table border="1"><thead><tr><th></th><th>From</th><th>To</th></tr></thead><tbody><tr><td>Wire Bonding Method</td><td>Single Stitch Bond on Lead post</td><td>Forward Bond on Lead post</td></tr></tbody></table>						From	To	Wire Bonding Method	Single Stitch Bond on Lead post	Forward Bond on Lead post
	From	To								
Wire Bonding Method	Single Stitch Bond on Lead post	Forward Bond on Lead post								
There is no product marking change as a result of this change.										
Reliability Summary										
QV DEVICE NAME: FDMF3170 RMS: F86119, W67764, F83348, F81535 PACKAGE: SPS56										
Test	Specification	Condition	Interval	Results						
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/231						
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/539						
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231						
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/77						
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231						



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Electrical Characteristics Summary:

Electrical Characteristics are not affected

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FDMF5068	FDMF3170
FDMF5085	FDMF3170
FDMF5062	FDMF3170
FDMF5071	FDMF3170